



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Charles A. Odegard, et al.

Art Unit: 2812

Serial No.: 10/729,128

Examiner: TBD

Filed: 12/05/03

Docket: TI-35691

For: Manufacturing System and Apparatus for Balanced Product Flow with Application
to Low-Stress Underfilling of Flip-Chip Electronic Devices

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited
with the U.S. Postal Service on 3-19-04 as
First Class Mail in an envelope addressed to: Commissioner for
Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Karen Vertz
Karen Vertz

3-19-04
Date

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Enclosed are **FIVE (5)** sheets of formal drawings for the above-referenced case.
Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments
Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated
P.O. Box 655474 M/S 3999
Dallas, Texas 75265

Respectfully submitted,

Gary C. Honeycutt

Gary C. Honeycutt
Reg. No. 20,250